

New generation Probe card Metrology Qualification Methodology

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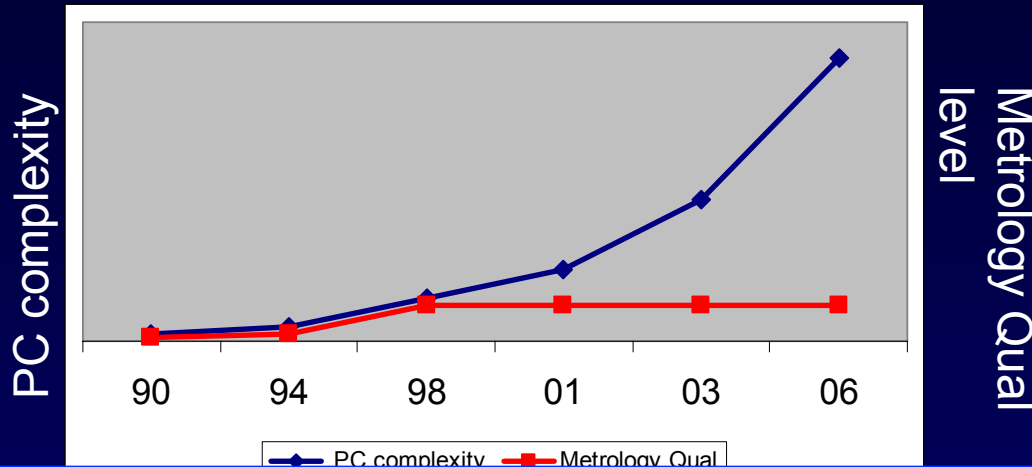


Agenda

- **Environment overview**
- **Operational sequence**
- **Repair objective**
- **Effective metrology**
- **Qualification method**
- **Summary**
- **Acknowledgments**

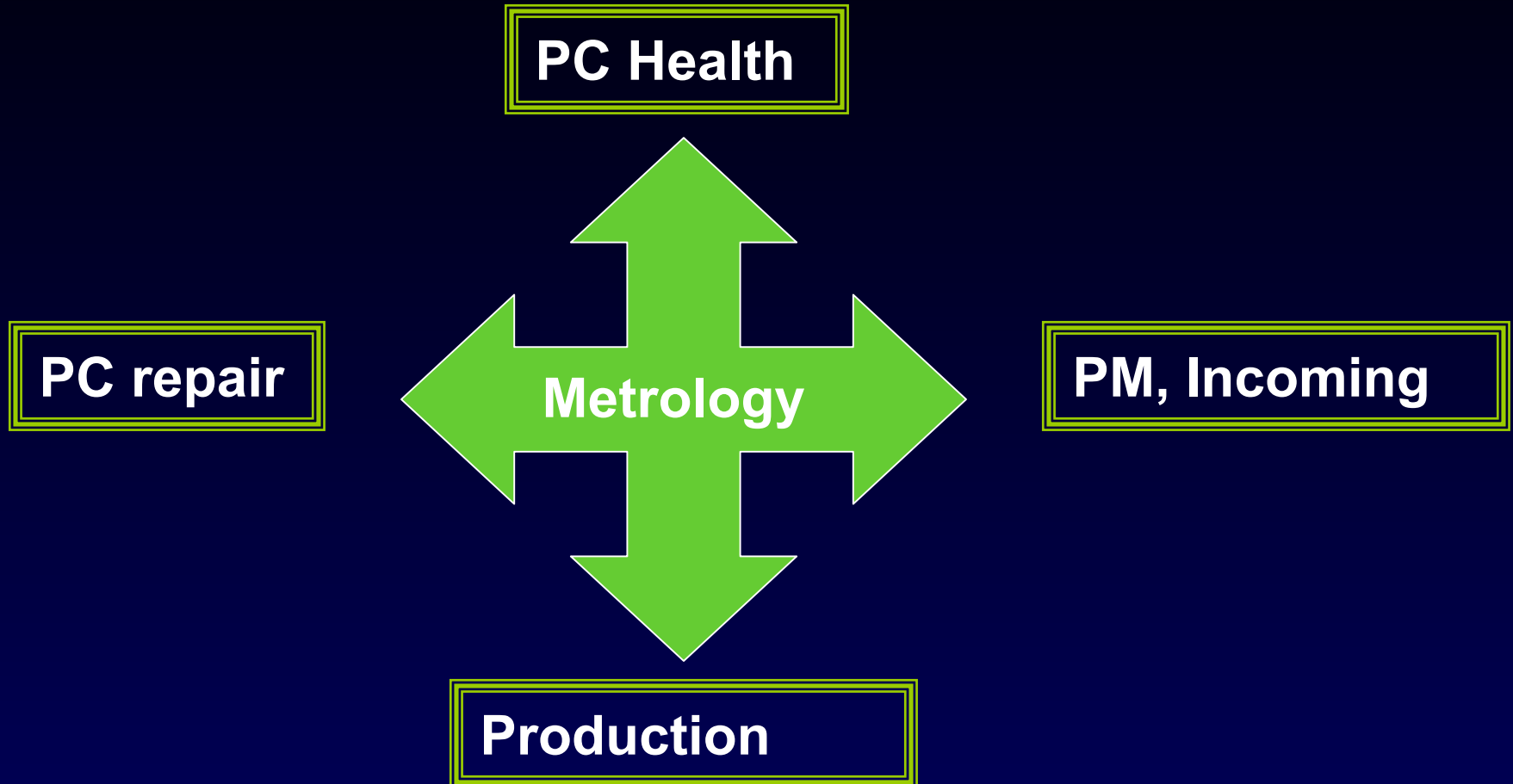
Probe Card (PC) Environment Overview

- Probe card cost has grown significantly in recent years
- Main cost of ownership are availability and effective utilization
- Probe card complexity growth challenge PCR environment and metrology
 - Probe count, probe design, pitch
- Metrology qualification hasn't developed at the same pace



Metrology qual method needs major improvement

PC Operational Sequence



Metrology is the center of probe card operational philosophy

Probe Card Repair Objective

- **Maximize PC Availability/Utilization**
 - To minimize inventory/buffer
 - To reduce PC validation time on tester
- **Metrology test results are used for probes X,Y,Z adjustment**
 - Efficient repair/PM increases MTBF and decreases MTTR
 - Indication for PC health

Effective PC repair is critical for today's wafer test technology

Effective Metrology

Safe

- Injury free environment for user
- Damage free environment for PC

Repeatable

- Sufficient precision in order to meet the P/T spec

Reliable

- Maintain precision and calibration over time
- Minimize test outliers

Independent

- Provides all necessary features for PC repair e.g. cleaning module, microscope, etc..

Correlative

- Reflects actual test process

Effective metrology is a key for efficient PC operation

Safety

Make ergonomic and safety machine per SEMI S2 & S8 standard. Damage free environment for PC

MCA

GR&R- comprehensive MCA study that will capture production environment variations

HVM

High Volume Manufacturing readiness: training, documentation, copy exactly systems

SPC

Excursion prevention systems – comprehensive SPC program including the PC supplier

Metrology correlation

Metrology/Test correlation – identify failure characteristics



Safety

Objective

- Injury free environment for the user
- Damage free environment for PC

Motivation

- Avoid injury to operator
- Avoid PC damage => unnecessary expense

Procedure

- SEMI S2 & S8 certification by the tool supplier
- Subjective Ergo evaluation by the customer
- Detail evaluation of the options for PC damage and develop correction items
 - Cleanliness, crashing

MCA

Objective:

- Metrology capability analysis
- Simulate day to day work

Motivation:

- Ensure system ability to provide test result during normal operations

Procedure:

- Check metrology repeatability for undisturbed batch
- Check metrology reproducibility- induce all day to day errors/disturbances
- Repeat on several PCs to cover PC to PC variation
- Repeat per PC technology

SPC Program

Objective:

- Excursion prevention systems

Motivation

- Prevent metrology from going out of control
 - Affects PC repair quality
- Monitor PC supplier quality and outgoing tests

Procedure

- Define local monitoring procedure
- Develop automated system
- Perform correlation study with PC supplier
- Implement preventive action to avoid incoming failure

Metrology/Test Correlation

Objective:

- Identify failure characteristics
- Metrology to Simulate the test process

Motivation

- Correlative metrology will make PC repair more efficient

Procedure

- Mother Board Design that emulates PC docking
- Test module accuracy study
- Scrub correlation
 - Metrology vs. Actual

HVM Readiness

Objective:

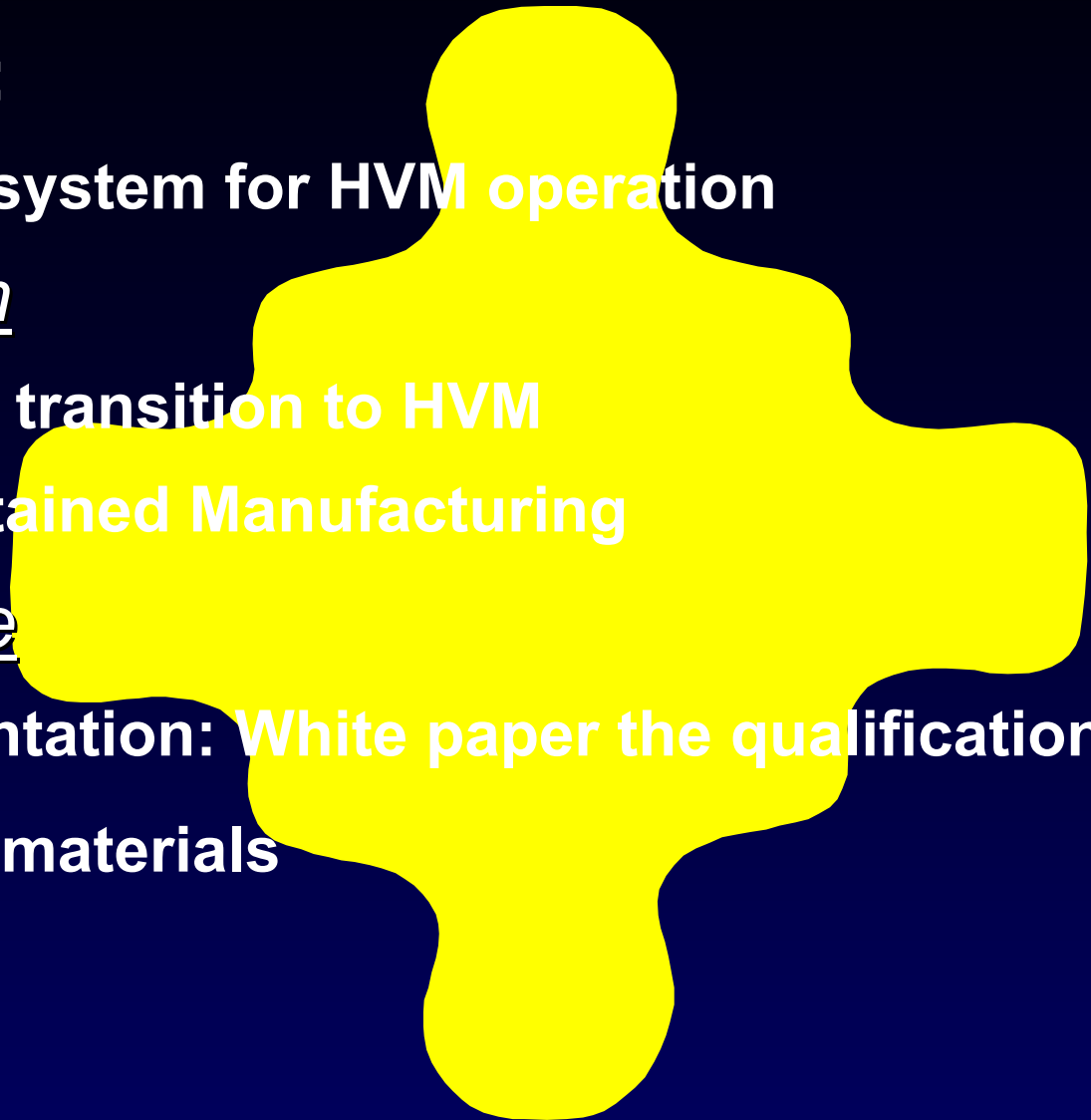
- Prepare system for HVM operation

Motivation

- Flawless transition to HVM
- Self Sustained Manufacturing

Procedure

- Documentation: White paper the qualification
- Training materials



Summary

- **Probe card price and complexity has risen significantly**
- **PC metrology qualification methodology is lagging behind technology development**
- **PC Metrology is a key entity in the PC environment**
- **Qualification Methodology has shown benefit for effective metrology**

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Backup

Terminology

- **Metrology- probe card metrology**
- **PCR - Probe Card Repair**
- **Qual – qualification**
- **PC – Probe Card**
- **PM – Preventive Maintenance**
- **Incoming – new PC acceptance**
- **HVM – high volume manufacturing**